EFFECT OF NANOPARTICLE FUNCTIONALIZATION AND AIR HUMIDITY ON THE DIELECTRIC PERFORMANCE OF EPOXY-BASED COMPOSITES

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Epoxy resins are abundantly used as insulating compounds. In order to enhance their dielectric properties, nanocomposites [1] of an epoxy/amine resin and one type of fillers (SiO₂, surface-silylated SiO₂, Al₂O₃, surface-silylated Al₂O₃, and BN; Figure 1) were prepared. The nanocomposites containing pristine silica showed the lowest permittivity of the series. An explanation can be derived from the Tanaka model [2]. Interaction of the functional groups of the polymer and the surface of the nanoparticles disturbs the mobility of dipoles in the polymer matrix, which decreases the permittivity. The dried samples acted as dielectrics over a broad frequency range (10^{-2} to 10^{6} Hz). Water absorption under ambient conditions significantly increased interfacial polarization and, consequently, deteriorated the insulating properties. This effect was most pronounced in the case of nanocomposites containing fillers such as pristine silica (Figure 1) with polar surfaces that are able to interact with water molecules. On the contrary, the composites containing nanoparticles with a hydrophobic surface (such as surface-silylated silica) showed good dielectric properties even upon the absorption of water.



Figure 1: Left: Surface functionalization of silica and alumina nanoparticles with hexamethyl disilazane. Right: Loss factors of pristine and surface-silylated silica nanoparticles (`wet´ and dried samples).

^[1] I. Plesa, P.V. Notingher, S. Schlögl, C. Sumereder, M. Muhr, Polymers 2016, 8, article 173 (63 pp.).

^[2] T. Tanaka, M. Kozako, N. Fuse, Y. Ohki, IEEE TDEI 2005, 12(4), 669-681.